

## **Conference News:**

### **CONFERENCES IN 2009:**

#### **2009 59th Electronic Components and Technology Conference (ECTC 2009)**

May 25-29, 2009 San Diego, CA USA [www.ectc.net](http://www.ectc.net)  
Contact: Jean Trehwella, [jeanmh@us.ibm.com](mailto:jeanmh@us.ibm.com)

#### **2009 19<sup>th</sup> IEEE Semiconductor Wafer Test Workshop (SWTW 2009)**

June 7-9, 2009 Paradise Point Resort, San Diego, CA USA  
[www.swtest.org](http://www.swtest.org)  
Contact: Maddie Harwood, [maddie@cemamerica.com](mailto:maddie@cemamerica.com)

#### **2009 17<sup>th</sup> European Microelectronics and Packaging Conference and Exhibition (EMPC 2009)**

June 15 -18, 2009 - Rimini – Italy [www.empc2009.org](http://www.empc2009.org)  
Contact: Pragma Congressi [segreteria@empc2009.org](mailto:segreteria@empc2009.org)

#### **2009 3<sup>rd</sup> IEEE International Workshop on Advances in Sensors and Interfaces (IWASI 2009)**

June 25-26, 2009 Trani, Italy  
[iwasi.poliba.it/iwasi2009](http://iwasi.poliba.it/iwasi2009)  
Contact: Prof. Daniela De Venuto, [d.devenuto@poliba.it](mailto:d.devenuto@poliba.it)

#### **2009 5th Annual Organic Microelectronics and Optoelectronics Workshop**

July 6-9, 2009, San Francisco CA, USA  
[acswebcontent.acs.org/organicmicroelectronic](http://acswebcontent.acs.org/organicmicroelectronic)  
Contact: [organic\\_microelectronics@acs.org](mailto:organic_microelectronics@acs.org)

#### **2009 International Conference on Electronics Packaging Technology/ High Density Design, Packaging and Microsystem Integration (ICEPT/HDP 2009)**

August 10-13, 2009 Beijing, China  
Contact: [icept2009@tsinghua.edu.cn](mailto:icept2009@tsinghua.edu.cn)

#### **2009 IEEE International Conference on Portable Information Devices (PORTABLE)**

September 21-22, 2009 Anchorage, AK USA  
[www.ieeevtc.org/portable2009](http://www.ieeevtc.org/portable2009)  
Contact: Ephraim Suhir [suhire@aol.com](mailto:suhire@aol.com)

#### **2009 3rd International Conference on 3D System Integration (3DIC 2009)**

September 28 – 30, 2009 San Francisco, CA, USA  
[www.3dic-conf.org](http://www.3dic-conf.org)  
Contact: P. Garrou [pgarrou@rti.org](mailto:pgarrou@rti.org)

#### **2009 31<sup>st</sup> Annual Electrical Overstress/Electrostatic Discharge Symposium (EOS/ESD 2009)**

30 August – 4 September 2009 Anaheim, CA, USA  
[www.esda.org](http://www.esda.org)  
Contact: Lisa Pimpinella [lpimpinella@esda.org](mailto:lpimpinella@esda.org)

#### **2009 15<sup>th</sup> Int'l Workshop on Thermal Investigations of ICs and Systems (THERMINIC 2009)**

October 7 – 9, 2009 Leuven, Belgium  
[cmp.imag.fr/conferences/therminic/therminic2009](http://cmp.imag.fr/conferences/therminic/therminic2009)  
Contact: Chantal Bénis-Morel, [chantal.benis@imag.fr](mailto:chantal.benis@imag.fr)

#### **2009 4<sup>th</sup> Int'l Microsystems, Packaging, Assembly and Circuits Technology (IMPACT 2009)**

October 21-23, 2009 Taipei, Taiwan  
[www.impact.org.tw/2009/General](http://www.impact.org.tw/2009/General)  
Contact: Ms.Yaffy Liu [service@impact.org.tw](mailto:service@impact.org.tw)

#### **2009 55th IEEE Holm Conference on Electrical Contacts (HOLM 2009)**

Sept. 14-16, 2009 Vancouver, BC, Canada  
[www.ewh.ieee.org/soc/cpmt/tc1](http://www.ewh.ieee.org/soc/cpmt/tc1)  
Contact: Alicia Zupeck [a.zupeck@ieee.org](mailto:a.zupeck@ieee.org)

#### **2009 18<sup>th</sup> IEEE Electrical Performance of Electronic Packaging (EPEP 2009)**

October 19-21, 2009 Portland, OR, USA  
[www.epep.org](http://www.epep.org)  
Contact: Kelly Sutton [epd@enr.arizona.edu](mailto:epd@enr.arizona.edu)

#### **2009 IEEE/CPMT Workshop on Accelerated Stress Test and Reliability (ASTR 2009)**

October 7-9 2009 Jersey City, NJ USA;  
[www.ewh.ieee.org/soc/cpmt/tc7/ast2009](http://www.ewh.ieee.org/soc/cpmt/tc7/ast2009)  
Contact: Cheryl Tulkoff [ctulkoff@austin.rr.com](mailto:ctulkoff@austin.rr.com)

#### **2009 11<sup>th</sup> Electronics Packaging Technology Conference (EPTC 2009)**

9-11 December 2009, Singapore  
[www.eptc-ieee.net](http://www.eptc-ieee.net)

#### **2009 IEEE Electrical Design of Advanced Packaging & Systems Symposium (EDAPS 2009)**

December 2-4, 2009 Hong Kong, China  
[www.edaps2009.org](http://www.edaps2009.org)  
Contact: [edaps2009@ee.cuhk.edu.hk](mailto:edaps2009@ee.cuhk.edu.hk)

### **CONFERENCES IN 2010:**

#### **2010 60th Electronic Components and Technology Conference (ECTC 2010)**

June 1 - 4, 2010 Las Vegas, NV, USA  
[www.ectc.net](http://www.ectc.net)  
Contact: Jean Trehwella, [jeanmh@us.ibm.com](mailto:jeanmh@us.ibm.com)

#### **3<sup>rd</sup> Electronics Systemintegration Technology Conference (ESTC 2010)**

September 13-16, 2010 Berlin, Germany  
[www.estc.biz/outlook\\_estc\\_2010](http://www.estc.biz/outlook_estc_2010)  
Contact: Rolf Aschenbrenner,  
[rolf.aschenbrenner@izm.fraunhofer.de](mailto:rolf.aschenbrenner@izm.fraunhofer.de)

See the CPMT Society website for updates:

[www.cpmpt.org/conf](http://www.cpmpt.org/conf)



## IEEE SW Test Workshop

### Semiconductor Wafer Test Workshop

June 7-10, 2009 San Diego, CA USA

The Workshop begins on Sunday afternoon with a topical tutorial, followed by a welcome reception, dinner, and a Keynote Speaker. The Technical Program starts Monday morning with 30-minute presentations in theme-oriented sessions. SW Test EXPO 2009 will showcase many of the key suppliers to the wafer probe industry and, as always, there will be ample opportunities for networking. The workshop concludes on Wednesday at Noon after an awards presentation and luncheon.

SWTW is a probe technology forum with a relaxed atmosphere held at a beautiful resort hotel and has ample time dedicated to informal discussions and networking. This year's special social activities a Casino Night at the Resort. Dinner will begin at 6:00 PM with the tables opening for play at 7:00 PM going until the closing raffles at 10:00 PM. It's fun times with fun money for all!

Conference registration includes all meals, refreshments, social activities, and technical program and exhibit attendance, as well as the printed proceedings distributed at the Workshop.

#### TOPICS:

- New probe card and contractor technologies
- Challenges of 300-mm wafer probing
- Monitor and reduction of chip I/O pad damage
- Area array and C4 solder bump probing
- Parallel, multi-site probing
- Probe Card PCB Characterization
- Productivity improvements for high volume production
- Probe data collection, analysis, and management
- Probe Card cleaning, extending card life, improving cost of ownership
- Advances in Probe Card Analyzers and metrology tools
- Addressing unique probing requirements:
  - Copper I/O pads - RF and microwave - Mixed signal, low noise, and parametric
  - Low-k dielectric and Probe Over Active Circuitry
  - Probing for Known Good Die
  - High power devices - Probe Potpourri (anything goes)

Visit [www.swtest.org](http://www.swtest.org)

## 11<sup>th</sup> International Conference on Electronic Materials and Packaging (EMAP 2009) Penang, Malaysia

Dec. 1-3, 2009

Call for Papers

The 11th Electronic Material and Packaging Conference (EMAP 2009) is an international event organized by the School of Mechanical Engineering, Universiti Sains Malaysia (USM), with technical co-sponsorship from the CPMT Society of IEEE. EMAP 2009 will feature short courses, technical sessions, and an exhibition.

This conference is an international forum of experts and researchers for the exchange, dissemination and discussion of state-of-the-art technologies and recent developments in electronic materials, packaging, manufacturing and assembly. Since 1999, EMAP has gained a reputation as a premier electronic materials and packaging conference in the Asia-Pacific region where most of the electronic packaging activities are taking place.

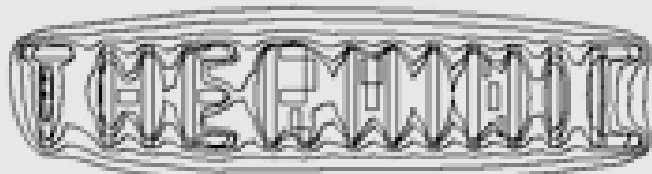
**Abstracts are solicited** to describe original and unpublished work. The abstract should be at least 500 words and it must clearly state the purpose, results (including data, drawings, graphs and photographs) and conclusion of the work.

The abstracts must be received by **June 15, 2009**. The final manuscript is due by October 1, 2009.

For more information, and the full Call for Papers, visit:

[mechanical.eng.usm.my/EMAP2009](http://mechanical.eng.usm.my/EMAP2009)

Visit EMAP the week before EPTC, in Singapore!



THERMINIC Workshops are a series of events to discuss the essential thermal questions of microelectronic microstructures and electronic parts in general. These questions are becoming more and more crucial with the increasing element density of circuits packaged together and with the move to nanotechnology. These trends are calling for thermal simulation, monitoring and cooling. Thermal management is expected to become an increasingly dominating factor of a system's cost. The growing power dissipated in a package, and the mobile parts of Microsystems, raise new thermal problems to be solved in the near future necessitating the regular discussion by the experts in these fields. Finally, there is an increasing need for accurate assessment of the boundary conditions used in the analysis of electronic parts, which requires a concurrent solution of the thermal behaviour of the whole system.

## 15th International Workshop on Thermal investigations of ICs and Systems

Leuven, Belgium -- 7-9 October 2009

This year THERMINIC will address in addition to the "traditional" thermal management problems, also stress and thermal-stress-related-reliability issues, both in micro- and opto-electronics fields. These issues, including various nanotechnology applications, are of significant importance and of high interest to the engineering community engaged in the field of thermal phenomena in "high-tech" systems.

**Leuven** is a university town located 30km to the east of Brussels. The workshop is hosted at the Faculty Club, a unique conference and banqueting centre, welcoming guests to the calm and tranquility of the 13th century Infirmerie of the Grand Beguinage and the Convent of Chièvres, built in 1561.

For information, and to register:

[cmp.imag.fr/conferences](http://cmp.imag.fr/conferences)



**IEEE NANO 2009**  
**July 26-30, 2009**  
**Genoa, Italy**

The conference brings together researchers, industry workers, entrepreneurs and funding agency leaders. It provides a forum for exchange of ideas, interaction, networking and collaboration for research and development in nanotechnology with special reference to the latest advances in nanotechnology.

CPMT's James Morris plans to have two sessions on nanotechnology in packaging applications.

For further information, and to register:

[www.medinfo.dist.unige.it/ieeenano2009](http://www.medinfo.dist.unige.it/ieeenano2009)

*Joint, with ACS and MRS, and IEEE-SSCS*

## Organic Microelectronics & Optoelectronics Workshop V

**July 6-9, 2009**  
**San Francisco**

The workshop brings together a broad spectrum of chemists, materials scientists, physicists, and engineers from both industry and academia in a stimulating forum to share information and ideas in the emerging fields of Organic Microelectronics and Optoelectronics. The goal is to build an interdisciplinary community working on applications such as RFIDs, displays, sensors, photovoltaics and optical devices while addressing some of the common scientific and manufacturing challenges to help these technologies advance in a more rapid, effective, and economical manner.

The technical program focuses on the areas of synthesis, theory, novel processing/ patterning/fabrication and device physics through a series of presentations by renowned invited speakers and poster sessions.

**Early-registration discounts through June 1.**

Visit our website:

[www.organicmicroelectronics.org](http://www.organicmicroelectronics.org)







JUNE 15<sup>TH</sup>-18<sup>TH</sup>, 2009 IN RIMINI - ITALY

# EMPC2009 EUROPEAN MICROELECTRONICS and PACKAGING CONFERENCE

The IMAPS EMPC, alternating annually with CPMT's ESTC, is Europe's premier conference planned every two years in a different European country, bringing together specialists from industry and academia.

The EMPC addresses "everything in electronics between the chip and the system".

**TUTORIALS:**

- Emerging Needs and Trends from 3D ICs to 3D Systems
- Physical and Electrical Design Modelling
- Electronics Reliability
- Recent trends in MEMS and BioMEMS packaging
- Advanced materials for High Power Electronics packaging

**SEMINARS:**

- Latest Advances in TSV Technology for 3D Integration
- Wirebonding



Exhibitors display equipment and programs.

EMPC is being held in Rimini, one of the most renowned bathing resort towns in Italy,

**TECHNICAL PROGRAM:**  
28 Sessions, plus Poster Sessions

Download the Advance Program – visit the website:

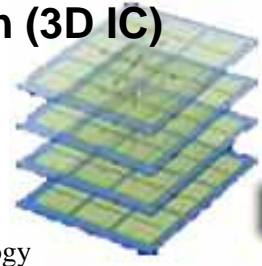
[www.empc2009.org](http://www.empc2009.org)

## IEEE International Conference on 3D System Integration (3D IC)

**September 28-30, 2009      San Francisco**

This conference combines the previous ASET and IEEE EDS Society sponsored **International 3D System Integration Conference**, held in Tokyo in 2007 & 2008, and the IEEE CPMT sponsored **3D System Integration Conference** held in 2005 & 2007 in Munich. The new, combined Conference will be held in San Francisco.

**3D IC** will cover all 3D IC topics, including 3D process technology, materials, equipment, circuits technology, design methodology and applications. The conference invites authors and attendees to submit and interact with 3D researchers from all around the world.




**TOPICAL AREAS:**

- 3D IC Technology
- 3D IC Circuits Technology
- 3D Applications
- 3D Design Methodology
- Test and Reliability of 3D Systems

To receive further information about 3D IC, or to register:

[www.3dic-conf.org](http://www.3dic-conf.org)



**ASTR 2009**

**Workshop on Accelerated Stress Testing & Reliability**

**October 7-9, 2009    Jersey City, NJ USA**

The purpose of the ASTR Workshop is to share ideas on better ways of accelerating and detecting hidden defects, flaws, and weaknesses in electronic and electro-mechanical hardware that would result in failures during usage.

For more information:

[www.ewh.ieee.org/soc/cpmt/tc7/ast2009](http://www.ewh.ieee.org/soc/cpmt/tc7/ast2009)

# EPTC 2009 Singapore

11<sup>th</sup> Electronics Packaging Technology Conference  
9<sup>th</sup> – 11<sup>th</sup> December 2009  
Shangri-La Hotel Singapore

**Mark Your Calendar  
for EPTC 2009**

## CALL FOR PAPERS

**Selected  
Publication in IEEE**

### ABOUT EPTC

The 11<sup>th</sup> Electronics Packaging Technology Conference (EPTC 2009) is an International event organized by the IEEE Reliability/CPMT/ED Singapore Chapter and sponsored by IEEE CPMT Society.

EPTC 2009 will feature technical sessions, short courses/forums, an exhibition, social and networking activities. It aims to provide a good coverage of technological developments in all areas of electronic packaging from design to manufacturing and operation. It is a major forum for the exchange of knowledge and provides opportunities to network and meet leading experts in the field.

Since its inauguration in 1997, EPTC has developed into a highly reputed electronics packaging conference in Asia and is well attended by experts in all aspects related to packaging technology from all over the world.

### CONFERENCE TOPICS

You are invited to submit an abstract, presenting new development in the following categories:

- ❑ **Advanced Packaging:** Wafer level packaging, 3D integration, TSV (through Silicon Via), embedded passives & actives on substrates, flip chip packaging, RF-ID, 3D SiP, Packaging solutions for MEMS, MOEMS, NEMS, Automotive electronics, optoelectronics
- ❑ **Interconnection Technologies:** wire bonding technology, flip chip technology, solder alternatives (ICP, ACP, ACF, NCP), under bump metallurgy, 3D and TSV connections, microbump, substrate technology,
- ❑ **Materials & Processes:** Materials and processes for traditional and advanced microelectronic systems, 3D packages, MEMS, solar, green and biomedical packaging that enhance mechanical, thermal, electrical and optical performance as well as cost effectiveness.
- ❑ **Modeling & Simulations:** Electrical Modeling & Signal Integrity, Thermal Characterization & Cooling Solutions: Mechanical Modeling & Structural Integrity
- ❑ **Quality & Reliability:** Component, board and system level reliability assessment, interfacial adhesion, accelerated testing and models, advances in reliability test methods and failure analysis.
- ❑ **Emerging Technology:** Packaging solutions for solar photovoltaic applications, systems and packaging in the areas of bioelectronics such as biomedical, bioengineering, biosensors and electronics for medical devices; wearable electronics, organic/printable electronics; portable power supplies such as fuel cells; and other novel packaging.

### IMPORTANT DATES

Submission of abstract	15th June 2009
Notification of Acceptance	1st August 2009
Submission of manuscript	1st October 2009

### ABSTRACT AND PAPER SUBMISSION

Abstracts are solicited to describe original and unpublished work. The abstract should be at least 500 words and it must clearly state the purpose, results (including data, drawings, graphs and photographs) and conclusion of the work. Key references to prior publications and how the work enhances existing knowledge should be included in the abstract as well.

Authors must designate two appropriate categories (found under CONFERENCE TOPICS) for abstract review. All submissions must be in English and should be made via the online submission system found at <http://www.eptc-ieee.net>. The required file format is Adobe Acrobat® PDF or MS Word in one single file for each submission.

The abstracts must be received by 15<sup>th</sup> June, 2009. Authors must include their affiliation, mailing address, telephone and fax numbers, and email address. Authors will be notified of paper acceptance and publication instruction by 1<sup>st</sup> August 2009. The final manuscript for publication in the conference proceedings is due by 1<sup>st</sup> October 2009. Selected papers will be published in IEEE/CPMT journals.

### OUTSTANDING TECHNICAL PAPERS

The conference proceeding is an official IEEE publication. Author(s) of Best Technical Paper and Best Student Paper will receive an award at the next conference.

### CALL FOR SHORT COURSES

The conference program includes short courses which will be conducted by leading experts in the field. Details will be updated in the conference website and available in subsequent mailings. Proposals for short courses can be submitted to [seungwook.yoon@statschippac.com](mailto:seungwook.yoon@statschippac.com).

### CALL FOR SPONSORSHIP / EXHIBITION PARTICIPATION

A tabletop exhibition featuring suppliers of materials, equipment, components, software and service providers of the microelectronics and electronic assembly industries will be held during the conference. Potential exhibitors and sponsors may email [secretariat@eptc-ieee.net](mailto:secretariat@eptc-ieee.net) for details.

General Chairs: Mr. James HOW / Mr. Yew Cheong MUI  
Technical Chair: Dr. Seung Wook YOON

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Conference information & contacts:

Website: <http://www.eptc-ieee.net>

Email: [secretariat@eptc-ieee.net](mailto:secretariat@eptc-ieee.net)



## **Future Directions in IC and Package Design Workshop (FDIP)**

**October 18, 2009, Portland, OR USA**

**Special Topic: What Research is Planned for EM Tools and How Are They Made Available to Computer Designers**

FDIP includes 7 talks on key topics; see the Advance Program for the listing. FDIP is held immediately before EPEP – be sure to schedule this extra day into your travel plans! Register by September 20<sup>th</sup>.

More information: [www.epeps.org](http://www.epeps.org)

*CPMT and MTT Societies*

**18th Conference on**

## **Electrical Performance of Electronic Packaging (EPEP 2009)**

**October 19-21, 2009  
Portland, Oregon USA**

**Abstracts Due: July 18, 2009**

The general subject of EPEP is the electrical modeling, design, analysis, and characterization of electronic interconnections and packaging structures. The goal is to be the leading conference dealing with advanced and emerging issues in electrical design of interconnect structures and assurance of Signal Integrity. Authors are invited to submit papers describing new technical contributions.

For full submittal details, please visit:

[www.epep.org](http://www.epep.org)

### **IEEE Components, Packaging and Manufacturing Technology Society**

Marsha Tickman, Executive Director  
PO Box 1331 / 445 Hoes Lane  
Piscataway, NJ 08855 USA

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[WWW.IEEE.ORG/mgm/](http://WWW.IEEE.ORG/mgm/)**

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**by Organizing and Attending**  
**Additional Information at [www.cpmt.org/conf/](http://www.cpmt.org/conf/)**

